

Serial number: 10/815,420

LISTING OF THE CLAIMS

Claim 1	currently amended
Claim 2	original
Claim 3	currently amended
Claim 4	canceled
Claim 5	currently amended
Claim 6	currently amended
Claim 7	currently amended
Claim 8	currently amended
Claim 9	original

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TEXT OF CLAIMS CURRENTLY UNDER EXAMINATION

1. (currently amended) A multilayer dicing die bonding film disposed between a semiconductor silicon wafer and a dicing support tape, the dicing die bonding film comprising
 - (a) Layer-1 adhesive, in contact with the dicing support tape, and
 - (b) Layer-2 adhesive, in contact with the semiconductor silicon wafer,in which the adhesion of Layer-2 to the silicon wafer is higher than the adhesion of Layer-1 to the dicing tape by at least 0.1N/cm, wherein exposure of the film to ultraviolet radiation is not required to enable release of the film from the dicing support tape.
2. (original) The dicing die bonding film of claim 1 in which the Layer-1 adhesive has a characteristic peel strength to the dicing tape in the range of 0.05 to less than 0.5 N/cm, and the Layer-2 adhesive has a characteristic peel strength to the semiconductor silicon wafer in the range of 0.5 to 10 N/cm.
3. (currently amended) The dicing die bonding film of claim 1 in which the Layer-1 adhesive comprises (a) thermoplastic rubber, (b) thermoset resin having a softening point above 60°C, (c) hardener, (d) accelerator, and (e) filler; and in which the Layer-2 adhesive comprises (a) ~~thermo-plastic~~ thermoplastic rubber, (b) thermoset resin in which at least 20% of the thermoset resin has a softening point below 60°C, (c) hardener, (d) accelerator, and (e) filler.
4. (canceled)
5. (currently amended) The dicing die bonding film of claim 3 ~~or claim 4~~ in which the thermoset resin in Layer-1 is a solid epoxy with a softening point of greater than 60°C and a weight per epoxy equivalent of 100 to 1000.

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6. (currently amended) The dicing die bonding film of claim 3 ~~or claim 4~~ in which the thermoset resin in Layer-2 is an epoxy having a softening point below 60°C and a weight per epoxy equivalent of 100 to 1000.
7. (currently amended) The dicing die bonding film of claim 3 ~~or claim 4~~ in which the thermoset resin in Layer-2 is a mixture of thermoset resins and at least 20% of the total Layer-2 thermoset resins have a softening point below 60°C.
8. (currently amended) The dicing die bonding film of claim 3 ~~or claim 4~~ in which the thermoplastic rubber is carboxy terminated butadiene-nitrile/epoxy adduct and nitrile butadiene rubber.
9. (original) The dicing die bonding film of claim 8 in which the carboxy terminated butadiene-nitrile/epoxy adduct consists of about 20-80 wt% carboxy terminated butadiene-nitrile and about 20-80 wt% diglycidyl ether bisphenol A : bisphenol A epoxy.